Excellent Integrated System Limited

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<u>Capital Advanced Technologies, Inc.</u> 33305

For any questions, you can email us directly: sales@integrated-circuit.com



Distributor of Capital Advanced Technologies, Inc.: Excellent Integrated System Limited Datasheet of 33305 - PROTOBOARD SMT FOR SOT-953

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SURFBOARDS®

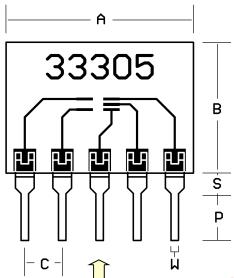
THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TAM



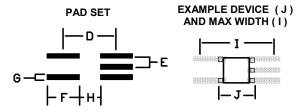
33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33305

MODEL **33305**



SINGLE-IN-LINE (SIP) PINS ON .100 in. CENTERS DRAWINGS NOT TO SCALE



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING.

SEE WEBSITE FOR SOLDERING SUGGESTIONS

ACCEPTS SOT-953

PARTIAL

5 LEAD .35 mm PITCH DEVICES DEVICE LEAD WIDTH 1.0 To Max 2.5 MM

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

Oversize Pads Permit hand soldering and accept a wide range of device widths and tolerances.

FIG.	MM	IN.	NOTE:
Α	12.7	.500	BOARD WIDTH +5mm .020in.
В	8.89	.350	BOARD HEIGHT +5mm .020in.
С	2.54	.100	SIP PIN SPACE +20mm .008in.
D	1.8	.071	PAD CENTERLINE
E	.35	.014	DEVICE LEAD PITCH
F	1.1	.043	PAD LENGTH
G	.2	.008	PAD WIDTH
Н	.7	.028	GAP
I	2.5	.098	MAX LEAD WIDTH
J	1.0	.039	TYPICAL LEAD WIDTH
Р	3.3	.130	LENGTH FROM SHOULDER +5mm .020in.
S	1.57	.062	PIN SHOULDER HEGHT
w	.5	.020	PIN WIDTH

TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Slight Variations due to manufacturing process can occur.

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent. CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +-.5mm .020in.



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MADE IN **USA**